

Thin Wafer Market by Wafer Size (125 mm, 200 mm, and 300 mm), Process (Temporary Bonding & Debonding and Carrier-less/Taiko Process), Technology, Application (MEMS, CIS, Memory, RF Devices, LED, Interposer, Logic) and Geography - Global Forecast to 2027

<https://marketpublishers.com/r/T12B3275BA4EN.html>

Date: September 2022

Pages: 193

Price: US\$ 4,950.00 (Single User License)

ID: T12B3275BA4EN

Abstracts

The thin wafer market is projected to grow from USD 11.4 billion in 2022 and is projected to reach USD 20.6 billion by 2027; it is expected to grow at a CAGR of 12.5% from 2022 to 2027.

Reducing sizes of electronic devices, rising adoption of MEMS technology in portable health monitoring devices, growing smartphone and consumer electronics markets and high amount of material saving is expected to fuel the growth of the thin wafer market.

However, issues related to efficiency maintenance is limiting the growth of the thin wafer market.

“Market for 200 mm wafers to hold a significant share during the forecast period.”

200 mm wafers are expected to witness significant demand majorly on account of their wide adoption in power devices, ICs, LEDs, MEMS, and many other semiconductor and electronic devices. The 200 mm wafers are affordable and can be easily integrated into various devices. As a result, these wafers are adopted on a large-scale basis by small-scale and large-scale electronic manufacturers. Furthermore, for the manufacturing of devices that require small die sizes and have a global shipment size in the thousands, these wafers are increasingly being used. LED, RF device, and power transistors

manufacturers use 200 mm silicon wafers.

In May 2022, Soitec (France) has released its first 200mm silicon carbide SmartSiC™ wafer. With the release, Soitec is able to enlarge its SiC product portfolio beyond 150mm, take the development of its SmartSiC™ wafers to the next level and cater to the growing demand of the automotive market.

“Wafer polishing equipment market is expected to grow at the highest CAGR during the forecast period”

The growth of the wafer polishing equipment market can be attributed to the increasing demand for thinner wafers to integrate microelectronics into various consumer electronic devices. The wafer polishing process creates thinner wafers compared to back-grinding alone and evens out any irregular topography and prevents warping that causes the wafers to weaken. Thus, there is an increased demand for wafer polishing equipment. Moreover, the increasing number of semiconductor fabrication plants in countries such as China and Taiwan, owing to growing investments in semiconductor manufacturing, is expected to contribute toward the growth of the wafer thinning equipment market.

“Asia Pacific to hold the largest share of the thin wafer market during the forecast period”

Asia Pacific is expected to hold the largest share of the thin wafer market during the forecast period. The Asia Pacific has witnessed large-scale adoption of smart electronic devices. This has led the consumer electronics manufacturers to launch higher-end devices in this region. The acceptance of the latest technology trends by majority of consumer electronics manufacturers have stimulated the demand for thinner wafers in Asia Pacific. In recent years, there has been a remarkable increase in the number of semiconductor fabrication plants and IC manufacturing firms in countries such as China and Taiwan, due to investments in semiconductor manufacturing this has paved way towards the growth of the thin wafer market in the Asia Pacific region.

In the process of determining and verifying the market size for several segments and subsegments gathered through secondary research, extensive primary interviews have been conducted with key industry experts in the thin wafer space. The break-up of primary participants for the report has been shown below:

By Company Type: Tier 1 –40%, Tier 2 – 40%, and Tier 3 – 20%

By Designation: C-level Executives – 40%, Directors –40%, and Others – 20%

By Region: Americas –33%, Asia Pacific– 45%, EMEA –22%

The report profiles key players in the thin wafer market with their respective market ranking analysis. Prominent players profiled in this report are include Shin-Etsu Chemical Co., Ltd. (Japan), SUMCO Corporation (Japan), GlobalWafers Co., Ltd. (Taiwan), Siltronic (Germany), SK Siltron (South Korea), SUSS MicroTec (Germany), DISCO Corporation (Japan), 3M (US), and Applied Materials (US Apart from these, Mechatronic Systemtechnik (Austria), Synova (Switzerland), EV Group (Austria), Wafer Works Corporation (Taiwan), Atecom technology Co., Ltd. (Taiwan), Siltronix Silicon Technologies (France), LDK Solar (China), UniversityWafer, Inc. (US) are among a few emerging companies in the thin wafer market.

Research Coverage:

This research report categorizes global thin wafer market based on wafer size, process, technology, application and geography. The report describes the major drivers, restraints, challenges, and opportunities pertaining to the thin wafer market and forecasts the same till 2027 (including analysis of COVID-19 impact on the market). Apart from these, the report also consists of leadership mapping and analysis of all the companies included in the thin wafer ecosystem.

Key Benefits of Buying the Report

The report would help leaders/new entrants in this market in the following ways:

1. This report segments the thin wafer market comprehensively and provides the closest market size projection for all subsegments across different regions.
2. The report helps stakeholders understand the pulse of the market and provides them with information on key drivers, restraints, challenges, and opportunities for market growth.
3. This report would help stakeholders understand their competitors better and gain more insights to improve their position in the business. The competitive landscape section includes competitor ecosystem, product developments and launches, partnerships, and mergers and acquisitions.
4. The analysis of the top 28 companies, based on the market rank as well as the

product footprint will help stakeholders visualize the market positioning of these key players.

5. Patent analysis, trade data, and technological trends that will shape the market in the coming years has also been covered in this report.

Contents

1 INTRODUCTION

1.1 STUDY OBJECTIVES

1.2 MARKET DEFINITION

1.3 STUDY SCOPE

1.3.1 MARKETS COVERED

1.3.2 INCLUSIONS AND EXCLUSIONS

1.3.3 REGIONAL SCOPE

1.3.4 YEARS CONSIDERED

1.4 CURRENCY

1.5 PACKAGE SIZE

1.6 STAKEHOLDERS

1.7 SUMMARY OF CHANGES

2 RESEARCH METHODOLOGY

2.1 RESEARCH DATA

FIGURE 1 THIN WAFER MARKET: RESEARCH DESIGN

2.1.1 SECONDARY DATA

2.1.1.1 Major secondary sources

2.1.1.2 Key data from secondary sources

2.1.2 PRIMARY DATA

2.1.2.1 Primary interviews with experts

2.1.2.2 Breakdown of primaries

2.1.3 SECONDARY AND PRIMARY RESEARCH

2.1.3.1 Key industry insights

2.2 MARKET SIZE ESTIMATION

FIGURE 2 MARKET SIZE ESTIMATION METHODOLOGY: REVENUE GENERATED BY KEY PLAYERS IN THIN WAFER MARKET

2.2.1 BOTTOM-UP APPROACH

2.2.1.1 Approach to capture market size by bottom-up analysis (demand side)

FIGURE 3 MARKET SIZE ESTIMATION METHODOLOGY: BOTTOM-UP APPROACH

2.2.2 TOP-DOWN APPROACH

2.2.2.1 Approach to capture market size by top-down analysis (supply side)

FIGURE 4 MARKET SIZE ESTIMATION METHODOLOGY: TOP-DOWN APPROACH

2.3 MARKET BREAKDOWN AND DATA TRIANGULATION

FIGURE 5 DATA TRIANGULATION

2.4 RESEARCH ASSUMPTIONS

FIGURE 6 ASSUMPTIONS FOR RESEARCH STUDY

2.5 RISK ASSESSMENT

2.6 LIMITATIONS

3 EXECUTIVE SUMMARY

3.1 GROWTH RATE ASSUMPTIONS/GROWTH FORECAST

FIGURE 7 300 MM WAFER TO ACCOUNT FOR LARGEST MARKET SHARE DURING FORECAST PERIOD

FIGURE 8 THIN WAFER MARKET, BY WAFER SIZE, 2022–2027 (MILLION SQUARE INCHES)

FIGURE 9 MEMORY APPLICATIONS TO DOMINATE THIN WAFER MARKET BY 2027

FIGURE 10 WAFER THINNING EQUIPMENT MARKET FOR LED APPLICATIONS TO GROW AT HIGHEST CAGR BETWEEN 2022 AND 2027

FIGURE 11 ASIA PACIFIC ACCOUNTED FOR LARGEST SHARE OF THIN WAFER MARKET IN 2021

4 PREMIUM INSIGHTS

4.1 ATTRACTIVE OPPORTUNITIES FOR PLAYERS IN THIN WAFER MARKET

FIGURE 12 THIN WAFERS EXPECTED TO WITNESS HIGH ADOPTION RATE DURING FORECAST PERIOD

4.2 WAFER THINNING EQUIPMENT MARKET, BY TECHNOLOGY

FIGURE 13 DICING TECHNOLOGY TO HOLD LARGEST MARKET SHARE DURING FORECAST PERIOD

4.3 THIN WAFER MARKET, BY APPLICATION

FIGURE 14 MARKET FOR LED EXPECTED TO GROW AT HIGHEST CAGR BETWEEN 2022 AND 2027

4.4 WAFER THINNING EQUIPMENT MARKET, BY TECHNOLOGY AND APPLICATION

FIGURE 15 MEMORY AND LOGIC TO BE MOST FAVORABLE APPLICATION AREAS FOR WAFER THINNING EQUIPMENT MARKET IN 2022

4.5 GEOGRAPHICAL ANALYSIS OF THIN WAFER MARKET

FIGURE 16 CHINA TO EXHIBIT HIGHEST CAGR IN THIN WAFER MARKET BETWEEN 2022 AND 2027

5 MARKET OVERVIEW

5.1 INTRODUCTION

5.2 MARKET DYNAMICS

FIGURE 17 THIN WAFER MARKET: DRIVERS, RESTRAINTS, OPPORTUNITIES, AND CHALLENGES

5.2.1 DRIVERS

5.2.1.1 Rising adoption of MEMS technology in portable health monitoring devices

5.2.1.2 Reducing size of electronic devices

5.2.1.3 Growing smartphone and consumer electronics markets

5.2.1.4 High amount of material saving

FIGURE 18 DRIVERS: IMPACT ANALYSIS

5.2.2 RESTRAINTS

5.2.2.1 Efficiency maintenance—major issue for thin wafers

FIGURE 19 RESTRAINTS: IMPACT ANALYSIS

5.2.3 OPPORTUNITIES

5.2.3.1 Expanding IC industry in China

5.2.3.2 Growing adoption of IoT and AI in automotive sector

FIGURE 20 GLOBAL IOT CONNECTIONS FORECAST BY 2025 (BILLION)

5.2.3.3 Rising adoption of portable devices

FIGURE 21 OPPORTUNITIES: IMPACT ANALYSIS

5.2.4 CHALLENGES

5.2.4.1 Volatility and susceptibility to damage caused by pressure or stress

FIGURE 22 CHALLENGES: IMPACT ANALYSIS

5.3 VALUE CHAIN ANALYSIS

FIGURE 23 VALUE CHAIN ANALYSIS: INTEGRATED DEVICE MANUFACTURERS ADD MAJOR VALUE

5.4 ECOSYSTEM/MARKET MAP

TABLE 1 PLAYERS AND THEIR ROLE IN ECOSYSTEM

5.5 TECHNOLOGY ANALYSIS

5.5.1 SILICON CARBIDE (SIC) TECHNOLOGY

TABLE 2 COMPARISON OF BENEFITS OF SIC TECHNOLOGY WITH OTHER TECHNOLOGIES

5.6 CASE STUDY ANALYSIS

5.6.1 STMICROELECTRONICS SELECTS CREE'S SILICON CARBIDE BARE AND EPITAXIAL WAFERS

5.6.2 INFINEON TECHNOLOGIES AND UMC ANNOUNCE MANUFACTURING AGREEMENT

5.6.3 GLOBALWAFERS CO., LTD. AND GLOBALFOUNDRIES ANNOUNCE

PARTNERSHIP TO EXPAND SEMICONDUCTOR WAFER SUPPLY

5.6.4 VTT USES OKMETIC'S E-SOI® WAFERS FOR ITS PHOTONICS TECHNOLOGY

5.6.5 SILTERRA MALAYSIA'S NEW MANUFACTURING TECHNOLOGY FOR MEMS AND PHOTONICS DEVICES USES OKMETIC'S C-SOI WAFERS

5.7 REGULATORY LANDSCAPE

5.8 PRICING ANALYSIS

TABLE 3 SELLING PRICE OF THIN WAFER

6 THIN WAFER MARKET, BY PROCESS

6.1 INTRODUCTION

FIGURE 24 TEMPORARY BONDER AND DEBONDER MARKET SIZE

6.2 TEMPORARY BONDING & DEBONDING

6.2.1 MARKET ADHESIVES

6.2.1.1 UV-release adhesives

6.2.1.2 Thermal-release adhesives

6.2.1.3 Solvent-release adhesives

6.3 CARRIER-LESS APPROACH (TAIKO PROCESS)

7 THIN WAFER MARKET, BY WAFER SIZE

7.1 INTRODUCTION

FIGURE 25 300 MM WAFER SEGMENT TO DOMINATE MARKET BETWEEN 2022 AND 2027

TABLE 4 THIN WAFER MARKET, BY WAFER SIZE, 2018–2021 (MILLION SQUARE INCHES)

TABLE 5 THIN WAFER MARKET, BY WAFER SIZE, 2022–2027 (MILLION SQUARE INCHES)

TABLE 6 THIN WAFER MARKET, BY WAFER SIZE, 2018–2021 (USD MILLION)

TABLE 7 THIN WAFER MARKET, BY WAFER SIZE, 2022–2027 (USD MILLION)

7.2 125 MM

7.2.1 ADOPTION OF LARGER DIAMETER WAFERS BY SEMICONDUCTOR MANUFACTURERS TO IMPACT SEGMENT

TABLE 8 125 MM: THIN WAFER MARKET, BY APPLICATION, 2018–2021 (MILLION SQUARE INCHES)

TABLE 9 125 MM: THIN WAFER MARKET, BY APPLICATION, 2022–2027 (MILLION SQUARE INCHES)

TABLE 10 125 MM: THIN WAFER MARKET, BY APPLICATION, 2018–2021 (USD

MILLION)

TABLE 11 125 MM: THIN WAFER MARKET, BY APPLICATION, 2022–2027 (USD MILLION)

7.3 200 MM

7.3.1 DEMAND FOR 200 MM WAFERS TO WITNESS STEADY GROWTH DURING FORECAST PERIOD

TABLE 12 200 MM: THIN WAFER MARKET, BY APPLICATION, 2018–2021 (MILLION SQUARE INCHES)

TABLE 13 200 MM: THIN WAFER MARKET, BY APPLICATION, 2022–2027 (MILLION SQUARE INCHES)

TABLE 14 200 MM: THIN WAFER MARKET, BY APPLICATION, 2018–2021 (USD MILLION)

TABLE 15 200 MM: THIN WAFER MARKET, BY APPLICATION, 2022–2027 (USD MILLION)

7.4 300 MM

7.4.1 300 MM WAFER SEGMENT EXPECTED TO WITNESS FASTEST GROWTH DURING FORECAST PERIOD

TABLE 16 300 MM: THIN WAFER MARKET, BY APPLICATION, 2018–2021 (MILLION SQUARE INCHES)

TABLE 17 300 MM: THIN WAFER MARKET, BY APPLICATION, 2022–2027 (MILLION SQUARE INCHES)

TABLE 18 300 MM: THIN WAFER MARKET, BY APPLICATION, 2018–2021 (USD MILLION)

TABLE 19 300 MM: THIN WAFER MARKET, BY APPLICATION, 2022–2027 (USD MILLION)

8 THIN WAFER MARKET, BY APPLICATION

8.1 INTRODUCTION

FIGURE 26 THIN WAFER SHIPMENTS FOR LED APPLICATIONS TO GROW AT HIGHEST RATE BETWEEN 2022 AND 2027

TABLE 20 THIN WAFER MARKET, BY APPLICATION, 2018–2021 (MILLION SQUARE INCHES)

TABLE 21 THIN WAFER MARKET, BY APPLICATION, 2022–2027 (MILLION SQUARE INCHES)

FIGURE 27 MEMORY TO BE LARGEST APPLICATION IN THIN WAFERS MARKET IN 2022

TABLE 22 THIN WAFER MARKET, BY APPLICATION, 2018–2021 (USD MILLION)

TABLE 23 THIN WAFER MARKET, BY APPLICATION, 2022–2027 (USD MILLION)

TABLE 24 WAFER THINNING EQUIPMENT MARKET, BY APPLICATION, 2018–2021
(USD MILLION)

TABLE 25 WAFER THINNING EQUIPMENT MARKET, BY APPLICATION, 2022–2027
(USD MILLION)

8.2 MEMS

8.2.1 GROWTH ATTRIBUTED TO HIGH ADOPTION IN PORTABLE ELECTRONIC
DEVICES

TABLE 26 THIN WAFER MARKET FOR MEMS DEVICES, BY WAFER SIZE,
2018–2021 (MILLION SQUARE INCHES)

TABLE 27 THIN WAFER MARKET FOR MEMS DEVICES, BY WAFER SIZE,
2022–2027 (MILLION SQUARE INCHES)

TABLE 28 THIN WAFER MARKET FOR MEMS DEVICES, BY WAFER SIZE,
2018–2021 (USD MILLION)

TABLE 29 THIN WAFER MARKET FOR MEMS DEVICES, BY WAFER SIZE,
2022–2027 (USD MILLION)

TABLE 30 WAFER THINNING EQUIPMENT MARKET FOR MEMS APPLICATIONS,
BY REGION, 2018–2021 (USD MILLION)

TABLE 31 WAFER THINNING EQUIPMENT MARKET FOR MEMS APPLICATIONS,
BY REGION, 2022–2027 (USD MILLION)

8.3 CIS

8.3.1 INCREASING DEMAND FOR CIS FROM AUTOMOTIVE VERTICAL
EXPECTED TO DRIVE DEMAND

TABLE 32 THIN WAFER MARKET FOR CIS APPLICATIONS, BY WAFER SIZE,
2018–2021 (MILLION SQUARE INCHES)

TABLE 33 THIN WAFER MARKET FOR CIS APPLICATIONS, BY WAFER SIZE,
2022–2027 (MILLION SQUARE INCHES)

TABLE 34 THIN WAFER MARKET FOR CIS APPLICATIONS, BY WAFER SIZE,
2018–2021 (USD MILLION)

TABLE 35 THIN WAFER MARKET FOR CIS APPLICATIONS, BY WAFER SIZE,
2022–2027 (USD MILLION)

TABLE 36 WAFER THINNING EQUIPMENT MARKET FOR CIS APPLICATIONS, BY
REGION, 2018–2021 (USD MILLION)

TABLE 37 WAFER THINNING EQUIPMENT MARKET FOR CIS APPLICATIONS, BY
REGION, 2022–2027 (USD MILLION)

8.4 MEMORY

8.4.1 GROWING ADOPTION OF NAND FLASH MEMORY IN MOBILE
ELECTRONICS TO DRIVE DEMAND

TABLE 38 THIN WAFER MARKET FOR MEMORY DEVICES, BY WAFER SIZE,
2018–2021 (MILLION SQUARE INCHES)

TABLE 39 THIN WAFER MARKET FOR MEMORY DEVICES, BY WAFER SIZE, 2022–2027 (MILLION SQUARE INCHES)

TABLE 40 THIN WAFER MARKET FOR MEMORY DEVICES, BY WAFER SIZE, 2018–2021 (USD MILLION)

TABLE 41 THIN WAFER MARKET FOR MEMORY DEVICES, BY WAFER SIZE, 2022–2027 (USD MILLION)

TABLE 42 WAFER THINNING EQUIPMENT MARKET FOR MEMORY APPLICATIONS, BY REGION, 2018–2021 (USD MILLION)

TABLE 43 WAFER THINNING EQUIPMENT MARKET FOR MEMORY APPLICATIONS, BY REGION, 2022–2027 (USD MILLION)

8.5 RF DEVICES

8.5.1 GROWING ADOPTION OF RF DEVICES IN SMARTPHONES TO PROPEL MARKET GROWTH

TABLE 44 THIN WAFER MARKET FOR RF DEVICES, BY WAFER SIZE, 2018–2021 (MILLION SQUARE INCHES)

TABLE 45 THIN WAFER MARKET FOR RF DEVICES, BY WAFER SIZE, 2022–2027 (MILLION SQUARE INCHES)

TABLE 46 THIN WAFER MARKET FOR RF DEVICES, BY WAFER SIZE, 2018–2021 (USD MILLION)

TABLE 47 THIN WAFER MARKET FOR RF DEVICES, BY WAFER SIZE, 2022–2027 (USD MILLION)

TABLE 48 WAFER THINNING EQUIPMENT MARKET FOR RF DEVICES, BY REGION, 2018–2021 (USD MILLION)

TABLE 49 WAFER THINNING EQUIPMENT MARKET FOR RF DEVICES, BY REGION, 2022–2027 (USD MILLION)

8.6 LED

8.6.1 INCREASING DEMAND FOR LED COMPONENTS IN HOMES AND INFRASTRUCTURE TO DRIVE SEGMENT

TABLE 50 THIN WAFER MARKET FOR LED DEVICES, BY WAFER SIZE, 2018–2021 (MILLION SQUARE INCHES)

TABLE 51 THIN WAFER MARKET FOR LED DEVICES, BY WAFER SIZE, 2022–2027 (MILLION SQUARE INCHES)

TABLE 52 THIN WAFER MARKET FOR LED DEVICES, BY WAFER SIZE, 2018–2021 (USD MILLION)

TABLE 53 THIN WAFER MARKET FOR LED DEVICES, BY WAFER SIZE, 2022–2027 (USD MILLION)

TABLE 54 WAFER THINNING EQUIPMENT MARKET FOR LED DEVICES, BY REGION, 2018–2021 (USD MILLION)

TABLE 55 WAFER THINNING EQUIPMENT MARKET FOR LED DEVICES, BY

REGION, 2022–2027 (USD MILLION)

8.7 INTERPOSERS

8.7.1 NEED FOR ADVANCED ARCHITECTURE IN MINIATURE ELECTRONIC DEVICES TO DRIVE DEMAND

TABLE 56 THIN WAFER MARKET FOR INTERPOSERS, BY WAFER SIZE, 2018–2021 (MILLION SQUARE INCHES)

TABLE 57 THIN WAFER MARKET FOR INTERPOSERS, BY WAFER SIZE, 2022–2027 (MILLION SQUARE INCHES)

TABLE 58 THIN WAFER MARKET FOR INTERPOSERS, BY WAFER SIZE, 2018–2021 (USD MILLION)

TABLE 59 THIN WAFER MARKET FOR INTERPOSERS, BY WAFER SIZE, 2022–2027 (USD MILLION)

TABLE 60 WAFER THINNING EQUIPMENT MARKET FOR INTERPOSERS, BY REGION, 2018–2021 (USD MILLION)

TABLE 61 WAFER THINNING EQUIPMENT MARKET FOR INTERPOSERS, BY REGION, 2022–2027 (USD MILLION)

8.8 LOGIC

8.8.1 HIGH PENETRATION OF AFFORDABLE CLOUD COMPUTING SOLUTIONS TO DRIVE DEMAND

TABLE 62 THIN WAFER MARKET FOR LOGIC DEVICES, BY WAFER SIZE, 2018–2021 (MILLION SQUARE INCHES)

TABLE 63 THIN WAFER MARKET FOR LOGIC DEVICES, BY WAFER SIZE, 2022–2027 (MILLION SQUARE INCHES)

TABLE 64 THIN WAFER MARKET FOR LOGIC DEVICES, BY WAFER SIZE, 2018–2021 (USD MILLION)

TABLE 65 THIN WAFER MARKET FOR LOGIC DEVICES, BY WAFER SIZE, 2022–2027 (USD MILLION)

TABLE 66 WAFER THINNING EQUIPMENT MARKET LOGIC APPLICATIONS, BY REGION, 2018–2021 (USD MILLION)

TABLE 67 WAFER THINNING EQUIPMENT MARKET FOR LOGIC APPLICATIONS, BY REGION, 2022–2027 (USD MILLION)

8.9 OTHERS

TABLE 68 THIN WAFER MARKET FOR OTHER APPLICATIONS, BY WAFER SIZE, 2018–2021 (MILLION SQUARE INCHES)

TABLE 69 THIN WAFER MARKET FOR OTHER APPLICATIONS, BY WAFER SIZE, 2022–2027 (MILLION SQUARE INCHES)

TABLE 70 THIN WAFER MARKET FOR OTHER APPLICATIONS, BY WAFER SIZE, 2018–2021 (USD MILLION)

TABLE 71 THIN WAFER MARKET FOR OTHER APPLICATIONS, BY WAFER SIZE,

2022–2027 (USD MILLION)

TABLE 72 WAFER THINNING EQUIPMENT MARKET FOR OTHER APPLICATIONS, BY REGION, 2018–2021 (USD MILLION)

TABLE 73 WAFER THINNING EQUIPMENT MARKET FOR OTHER APPLICATIONS, BY REGION, 2022–2027 (USD MILLION)

9 THIN WAFER MARKET, BY TECHNOLOGY

9.1 INTRODUCTION

FIGURE 28 WAFER POLISHING EQUIPMENT MARKET TO GROW AT HIGHEST CAGR BETWEEN 2022 AND 2027

TABLE 74 WAFER THINNING EQUIPMENT MARKET, BY TECHNOLOGY, 2018–2021 (USD MILLION)

TABLE 75 WAFER THINNING EQUIPMENT MARKET, BY TECHNOLOGY, 2022–2027 (USD MILLION)

9.2 WAFER GRINDING

9.2.1 ATTRACTIVE FOR USE IN MINIATURIZATION OF SEMICONDUCTOR DEVICES

TABLE 76 WAFER GRINDING EQUIPMENT MARKET, BY APPLICATION, 2018–2021 (USD MILLION)

TABLE 77 WAFER GRINDING EQUIPMENT MARKET, BY APPLICATION, 2022–2027 (USD MILLION)

TABLE 78 WAFER GRINDING EQUIPMENT MARKET, BY REGION, 2018–2021 (USD MILLION)

TABLE 79 WAFER GRINDING EQUIPMENT MARKET, BY REGION, 2022–2027 (USD MILLION)

9.3 WAFER POLISHING

9.3.1 DEMAND FOR THIN WAFERS WITH SMOOTH SURFACE FOR SEAMLESS INTEGRATION TO DRIVE SEGMENT

TABLE 80 WAFER POLISHING EQUIPMENT MARKET, BY APPLICATION, 2018–2021 (USD MILLION)

TABLE 81 WAFER POLISHING EQUIPMENT MARKET, BY APPLICATION, 2022–2027 (USD MILLION)

TABLE 82 WAFER POLISHING EQUIPMENT MARKET, BY REGION, 2018–2021 (USD MILLION)

TABLE 83 WAFER POLISHING EQUIPMENT MARKET, BY REGION, 2022–2027 (USD MILLION)

9.4 WAFER DICING

9.4.1 WAFER DICING EQUIPMENT TO ACCOUNT FOR LARGEST MARKET

SHARE DURING FORECAST PERIOD

TABLE 84 WAFER DICING EQUIPMENT MARKET, BY APPLICATION, 2018–2021
(USD MILLION)

TABLE 85 WAFER DICING EQUIPMENT MARKET, BY APPLICATION, 2022–2027
(USD MILLION)

TABLE 86 WAFER DICING EQUIPMENT MARKET, BY REGION, 2018–2021 (USD
MILLION)

TABLE 87 WAFER DICING EQUIPMENT MARKET, BY REGION, 2022–2027 (USD
MILLION)

10 THIN WAFER MARKET, BY GEOGRAPHY

10.1 INTRODUCTION

FIGURE 29 THIN WAFER MARKET: GEOGRAPHIC SNAPSHOT, 2022–2027

TABLE 88 THIN WAFER MARKET, BY REGION, 2018–2021 (USD MILLION)

TABLE 89 THIN WAFER MARKET, BY REGION, 2022–2027 (USD MILLION)

TABLE 90 WAFER THINNING EQUIPMENT MARKET, BY REGION, 2018–2021 (USD
MILLION)

TABLE 91 WAFER THINNING EQUIPMENT MARKET, BY REGION, 2022–2027 (USD
MILLION)

10.2 AMERICAS

FIGURE 30 AMERICAS: GEOGRAPHIC SNAPSHOT

TABLE 92 AMERICAS: THIN WAFER MARKET, BY COUNTRY, 2018–2021 (USD
MILLION)

TABLE 93 AMERICAS: THIN WAFER MARKET, BY COUNTRY, 2022–2027 (USD
MILLION)

TABLE 94 AMERICAS: WAFER THINNING EQUIPMENT MARKET, BY
APPLICATION, 2018–2021 (USD MILLION)

TABLE 95 AMERICAS: WAFER THINNING EQUIPMENT MARKET, BY
APPLICATION, 2022–2027 (USD MILLION)

10.2.1 US

10.2.1.1 US to lead thin wafer market in Americas during forecast period

10.2.2 CANADA

10.2.2.1 Government support to promote use of electric vehicles to drive market

10.2.3 REST OF AMERICAS

10.2.3.1 Growing demand for semiconductor devices from consumer electronics and automotive industries to fuel market growth

10.3 EMEA

FIGURE 31 EMEA: GEOGRAPHIC SNAPSHOT

TABLE 96 EMEA: THIN WAFER MARKET, BY COUNTRY, 2018–2021 (USD MILLION)

TABLE 97 EMEA: THIN WAFER MARKET, BY COUNTRY, 2022–2027 (USD MILLION)

TABLE 98 EMEA: WAFER THINNING EQUIPMENT MARKET, BY APPLICATION, 2018–2021 (USD MILLION)

TABLE 99 EMEA: WAFER THINNING EQUIPMENT MARKET, BY APPLICATION, 2022–2027 (USD MILLION)

10.3.1 UK

10.3.1.1 Increase in demand for portable medical devices to drive market

10.3.2 GERMANY

10.3.2.1 Growing adoption of MEMS sensors in automotive industry to drive market

10.3.3 FRANCE

10.3.3.1 Increased EV manufacturing to bolster market growth in France

10.3.4 REST OF EMEA

10.3.4.1 Dearth of thin wafer manufacturers ? opportunity for new investments in

Rest of EMEA

10.4 ASIA PACIFIC

FIGURE 32 ASIA PACIFIC: GEOGRAPHIC SNAPSHOT

TABLE 100 ASIA PACIFIC: THIN WAFER MARKET, BY COUNTRY, 2018–2021 (USD MILLION)

TABLE 101 ASIA PACIFIC: THIN WAFER MARKET, BY COUNTRY, 2022–2027 (USD MILLION)

TABLE 102 ASIA PACIFIC: WAFER THINNING EQUIPMENT MARKET, BY APPLICATION, 2018–2021 (USD MILLION)

TABLE 103 ASIA PACIFIC: WAFER THINNING EQUIPMENT MARKET, BY APPLICATION, 2022–2027 (USD MILLION)

10.4.1 TAIWAN

10.4.1.1 Presence of several fabrication facilities and IC manufacturing firms to drive market

10.4.2 CHINA

10.4.2.1 China's focus on achieving 70% IC self-sufficiency by 2025 to drive market

10.4.3 JAPAN

10.4.3.1 Presence of major market players and end-use industries to drive market

10.4.4 SOUTH KOREA

10.4.4.1 South Korea expected to account for largest share of Asia Pacific market during forecast period

10.4.5 REST OF ASIA PACIFIC

10.4.5.1 Growing demand for connected devices to drive market in Rest of Asia Pacific

11 COMPETITIVE LANDSCAPE

11.1 COMPETITIVE LANDSCAPE

TABLE 104 THIN WAFER MARKET: KEY GROWTH STRATEGIES ADOPTED BY COMPANIES FROM 2019 TO 2022

11.2 REVENUE ANALYSIS OF TOP FIVE COMPANIES

FIGURE 33 THREE-YEAR REVENUE ANALYSIS OF TOP FIVE PLAYERS IN THIN WAFER MARKET

11.3 MARKET SHARE ANALYSIS (2021)

TABLE 105 THIN WAFER MARKET: DEGREE OF COMPETITION

11.4 COMPANY EVALUATION MATRIX

11.4.1 STARS

11.4.2 EMERGING LEADERS

11.4.3 PERVASIVE PLAYERS

11.4.4 PARTICIPANTS

FIGURE 34 THIN WAFER MARKET, COMPANY EVALUATION MATRIX, 2021

11.5 START-UP/SME EVALUATION MATRIX

11.5.1 PROGRESSIVE COMPANIES

11.5.2 RESPONSIVE COMPANIES

11.5.3 DYNAMIC COMPANIES

11.5.4 STARTING BLOCKS

FIGURE 35 THIN WAFER MARKET, START-UP/SME EVALUATION QUADRANT, 2021

11.6 THIN WAFER MARKET: COMPANY FOOTPRINT

TABLE 106 COMPANY FOOTPRINT

TABLE 107 COMPANY WAFER SIZE FOOTPRINT

TABLE 108 COMPANY APPLICATION FOOTPRINT

TABLE 109 COMPANY REGIONAL FOOTPRINT

11.7 COMPETITIVE SITUATIONS AND TRENDS

11.7.1 PRODUCT LAUNCHES

TABLE 110 PRODUCT LAUNCHES, 2019–2022

11.7.2 DEALS

TABLE 111 DEALS, 2019–2022

11.7.3 OTHERS

TABLE 112 EXPANSION, 2019–2022

12 COMPANY PROFILES

(Business Overview, Products Offered, Recent Developments, and MnM View (Key

strengths/Right to Win, Strategic Choices Made, and Weaknesses and Competitive Threats))*

12.1 INTRODUCTION

12.2 KEY PLAYERS

12.2.1 SK SILTRON

TABLE 113 SK SILTRON: BUSINESS OVERVIEW

FIGURE 36 SK SILTRON: COMPANY SNAPSHOT

12.2.2 SHIN-ETSU CHEMICAL CO., LTD.

TABLE 114 SHIN-ETSU CHEMICAL CO., LTD.: BUSINESS OVERVIEW

FIGURE 37 SHIN-ETSU CHEMICAL CO., LTD.: COMPANY SNAPSHOT

12.2.3 SILTRONIC

TABLE 115 SILTRONIC: BUSINESS OVERVIEW

FIGURE 38 SILTRONIC: COMPANY SNAPSHOT

12.2.4 SUMCO CORPORATION

TABLE 116 SUMCO CORPORATION: BUSINESS OVERVIEW

FIGURE 39 SUMCO CORPORATION: COMPANY SNAPSHOT

12.2.5 GLOBALWAFERS CO., LTD.

TABLE 117 GLOBALWAFERS CO., LTD.: BUSINESS OVERVIEW

FIGURE 40 GLOBALWAFERS CO., LTD.: COMPANY SNAPSHOT

12.2.6 SOITEC

TABLE 118 SOITEC: BUSINESS OVERVIEW

FIGURE 41 SOITEC: COMPANY SNAPSHOT

12.2.7 SUSS MICROTEC

TABLE 119 SUSS MICROTEC: BUSINESS OVERVIEW

FIGURE 42 SUSS MICROTEC: COMPANY SNAPSHOT

12.2.8 DISCO CORPORATION

TABLE 120 DISCO CORPORATION: BUSINESS OVERVIEW

FIGURE 43 DISCO CORPORATION: COMPANY SNAPSHOT

12.2.9 OKMETIC

TABLE 121 OKMETIC: BUSINESS OVERVIEW

12.2.10 3M

TABLE 122 3M: BUSINESS OVERVIEW

FIGURE 44 3M: COMPANY SNAPSHOT

12.2.11 APPLIED MATERIALS

TABLE 123 APPLIED MATERIALS: BUSINESS OVERVIEW

FIGURE 45 APPLIED MATERIALS: COMPANY SNAPSHOT

12.3 OTHER COMPANIES

12.3.1 MECHATRONIC SYSTEMTECHNIK

12.3.2 SYNOVA

- 12.3.3 EV GROUP
- 12.3.4 BREWER SCIENCE
- 12.3.5 WAFER WORKS CORPORATION
- 12.3.6 ATECOM TECHNOLOGY CO., LTD.
- 12.3.7 SIL'TRONIX SILICON TECHNOLOGIES
- 12.3.8 LDK SOLAR
- 12.3.9 PV CRYSTALOX SOLAR PLC
- 12.3.10 UNIVERSITYWAFER, INC
- 12.3.11 SHANGHAI SIMGUI TECHNOLOGY CO., LTD
- 12.3.12 VIRGINIA SEMICONDUCTOR INC
- 12.3.13 SILICON VALLEY MICROELECTRONICS
- 12.3.14 WAFER WORLD INC.

*Details on Business Overview, Products Offered, Recent Developments, and MnM View (Key strengths/Right to Win, Strategic Choices Made, and Weaknesses and Competitive Threats) might not be captured in case of unlisted companies.

13 APPENDIX

- 13.1 DISCUSSION GUIDE
- 13.2 KNOWLEDGE STORE: MARKETSandMARKETS' SUBSCRIPTION PORTAL
- 13.3 CUSTOMIZATION OPTIONS
- 13.4 RELATED REPORTS
- 13.5 AUTHOR DETAILS

I would like to order

Product name: Thin Wafer Market by Wafer Size (125 mm, 200 mm, and 300 mm), Process (Temporary Bonding & Debonding and Carrier-less/Taiko Process), Technology, Application (MEMS, CIS, Memory, RF Devices, LED, Interposer, Logic) and Geography - Global Forecast to 2027

Product link: <https://marketpublishers.com/r/T12B3275BA4EN.html>

Price: US\$ 4,950.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/T12B3275BA4EN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below
and fax the completed form to +44 20 7900 3970